



**NetVia Group is a one-stop source for quality printed circuit boards (PCBs). Prototypes, quick turns, low volume/high mix, and high volume are all within our proven capabilities.**

**But NetVia Group isn't just about fabricating boards, we're about partnerships. From your very first contact with us, through shipment of product, we're there to help with design issues, delivery requirements, and to provide high quality Printed Circuit Boards.**

- ISO Certified
- IPC Class II and III
- Mil-P-55110
- UL 94V-0
- RoHS Compliant
- Quick Turn Protos
- Low Volume/High Mix
- Production

DESCRIPTION	STANDARD	ADVANCED
<b>LINE / SPACE</b>		
Inner layer trace width / spacing (0.5 oz)	4/4	2.5/2.5
Inner layer trace width / spacing (1 oz)	5/5	3/4
Outer layer trace width / spacing (1 oz)	5/5	3/4
Outer layer trace width / spacing (2 oz)	8/8	6/6
<b>MECHANICAL / TOLERANCE</b>		
Aspect ratio	12:1	20:1
Minimum drill size (mechanical)	0.012"	0.006"
<b>Minimum drill size (laser)</b>	<b>0.005"</b>	<b>0.003"</b>
Minimum pad size over drill (outer layer)	0.010"	0.006"
Minimum pad size over drill (inner layer)	0.020"	0.010"
Blind vias available	Yes	Yes
Buried vias available	Yes	Yes
<b>Cavity / pocket mill</b>	<b>No</b>	<b>Yes</b>
Plated through hole size tolerance (+/- mils)	3	2
Drill position accuracy (+/- mils)	3	2
Layer count	12	38
Layer to layer registration (+/- mils)	5	3
Minimum core thickness	0.004"	0.002"
Minimum finished PCB thickness	0.020"	0.012"
Maximum finished PCB thickness	0.125"	0.500"
<b>FINISHES</b>		
HASL (hot air solder level) / 63% Tin / 37% Lead	Yes	Yes
HASL (hot air solder level) / Lead free / SN100CL	No	Yes
Electroless Nickel - 100u" / Immersion Gold - 3u" (ENIG)	Yes	Yes
Electroless Nickel - 100u" / Immersion Gold - 5u" (ENIG)	No	Yes
Electroless Nickel - 100u" / Electroless Palladium - 8u" Immersion Gold - 3u" (ENEPIG)	Yes	Yes
Immersion Silver	Yes	Yes
Immersion Tin	Yes	Yes
OSP (Entek Cu106A)	No	Yes
Selective hard Gold plate up to 50u"	No	Yes
Carbon ink	No	Yes
<b>VIP / non-conductive via fill (PP-2795 and PHP-900)</b>	<b>Yes</b>	<b>Yes</b>
<b>Conductive via fill (Tatsuta AE-3030)</b>	<b>No</b>	<b>Yes</b>
<b>LAMINATES</b>		
FR4 - Tg 145 (IPC-4101/21)	Yes	Yes
FR4 - Tg 170 (IPC-4101/24 or /26)	Yes	Yes
FR4 - Tg 170+ for RoHS (IPC-4101/124)	Yes	Yes
Getek/FR408HR	Yes	Yes
RO4003/4350 (RO4000 series laminates)	Yes	Yes
Aluminum/Copper metal back	No	Yes
Polyimide	Yes	Yes
Teflon (RO5880, RO3006, RO6002, TLY, TLX)	Yes	Yes
Fastrise, 2929 bondply, 6700 bonding films	Yes	Yes
Flex	Yes	Yes
Rigid - Flex	No	Yes

- Advanced / unique technologies in red font -

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